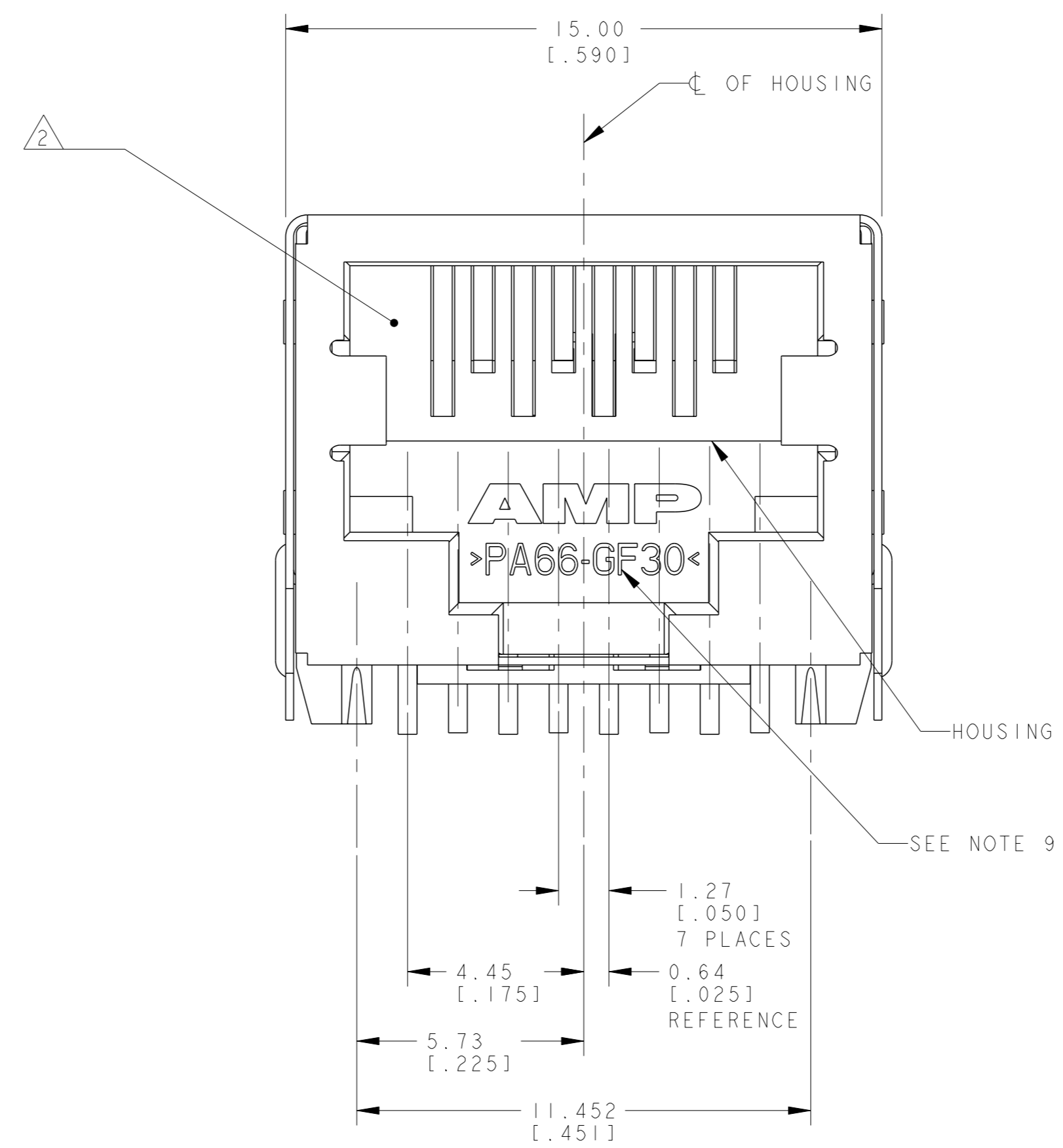
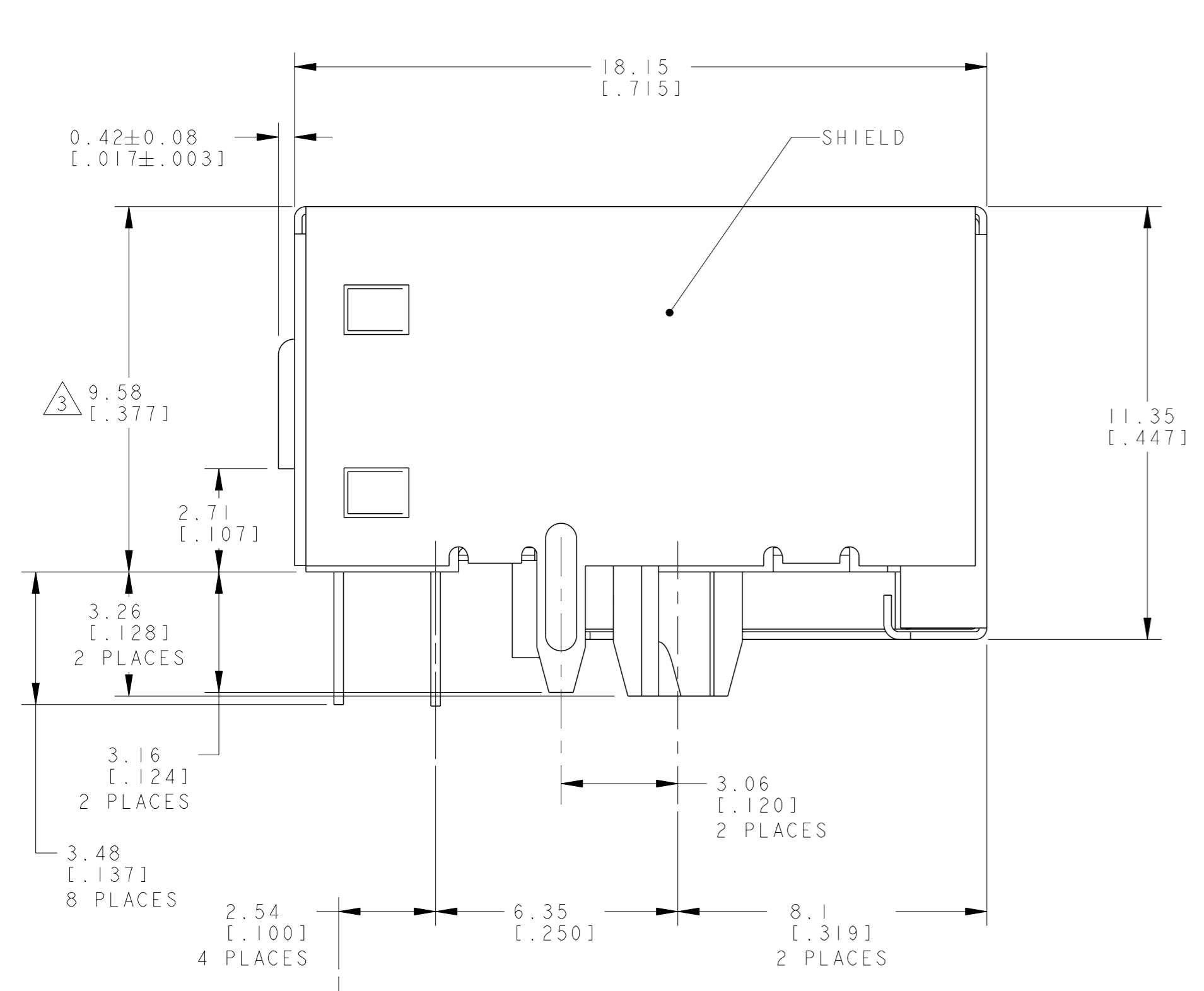
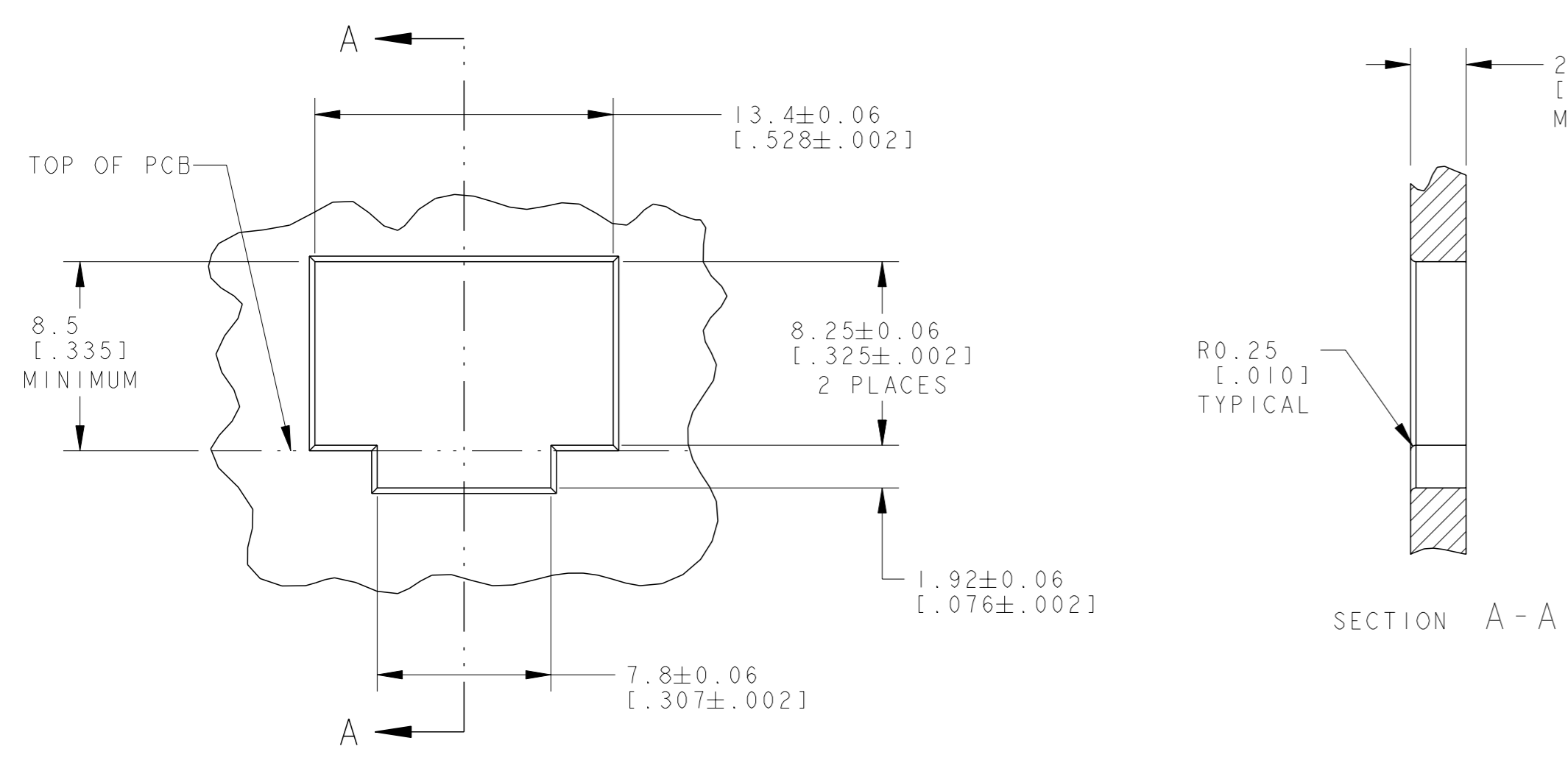
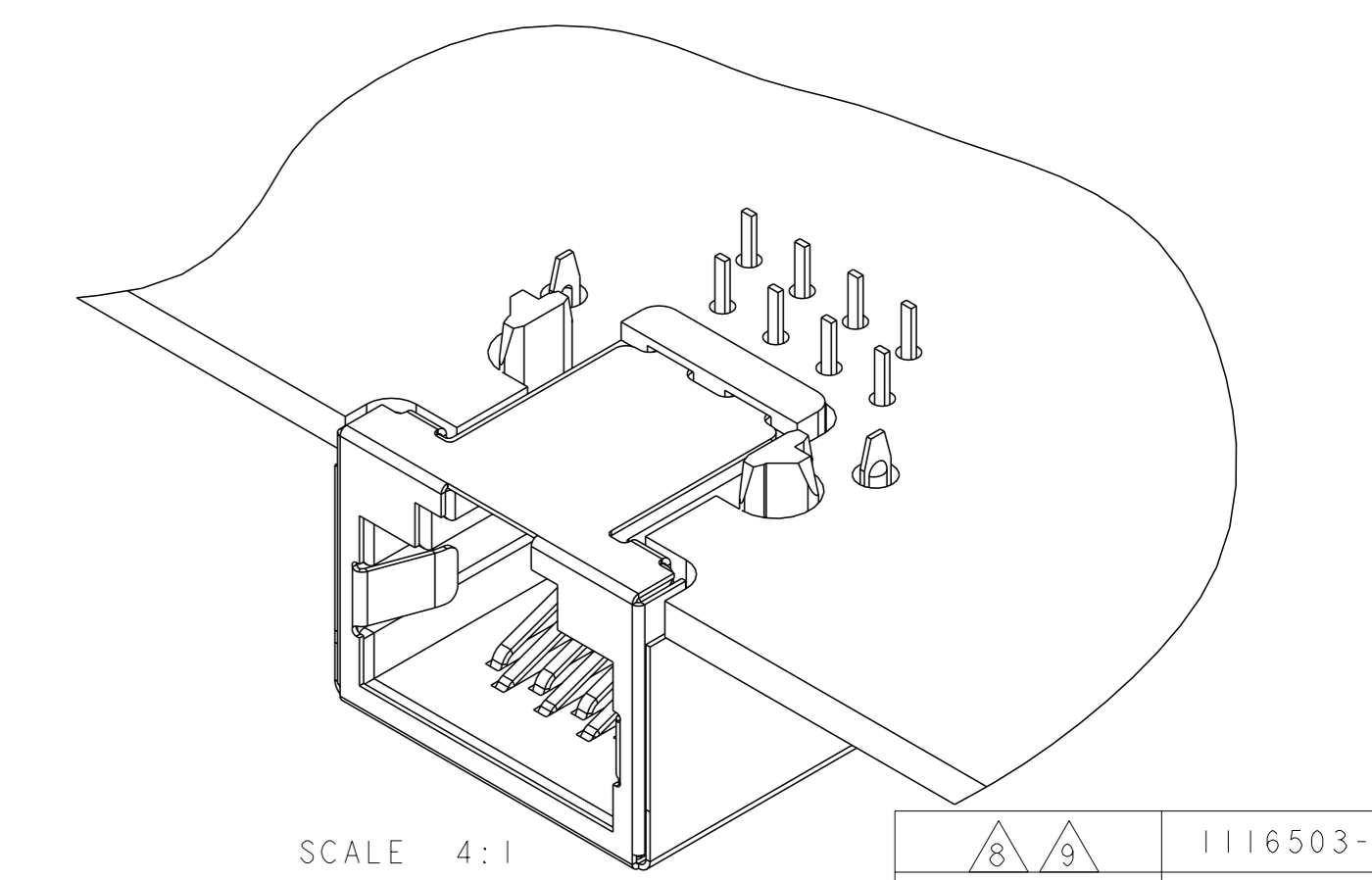
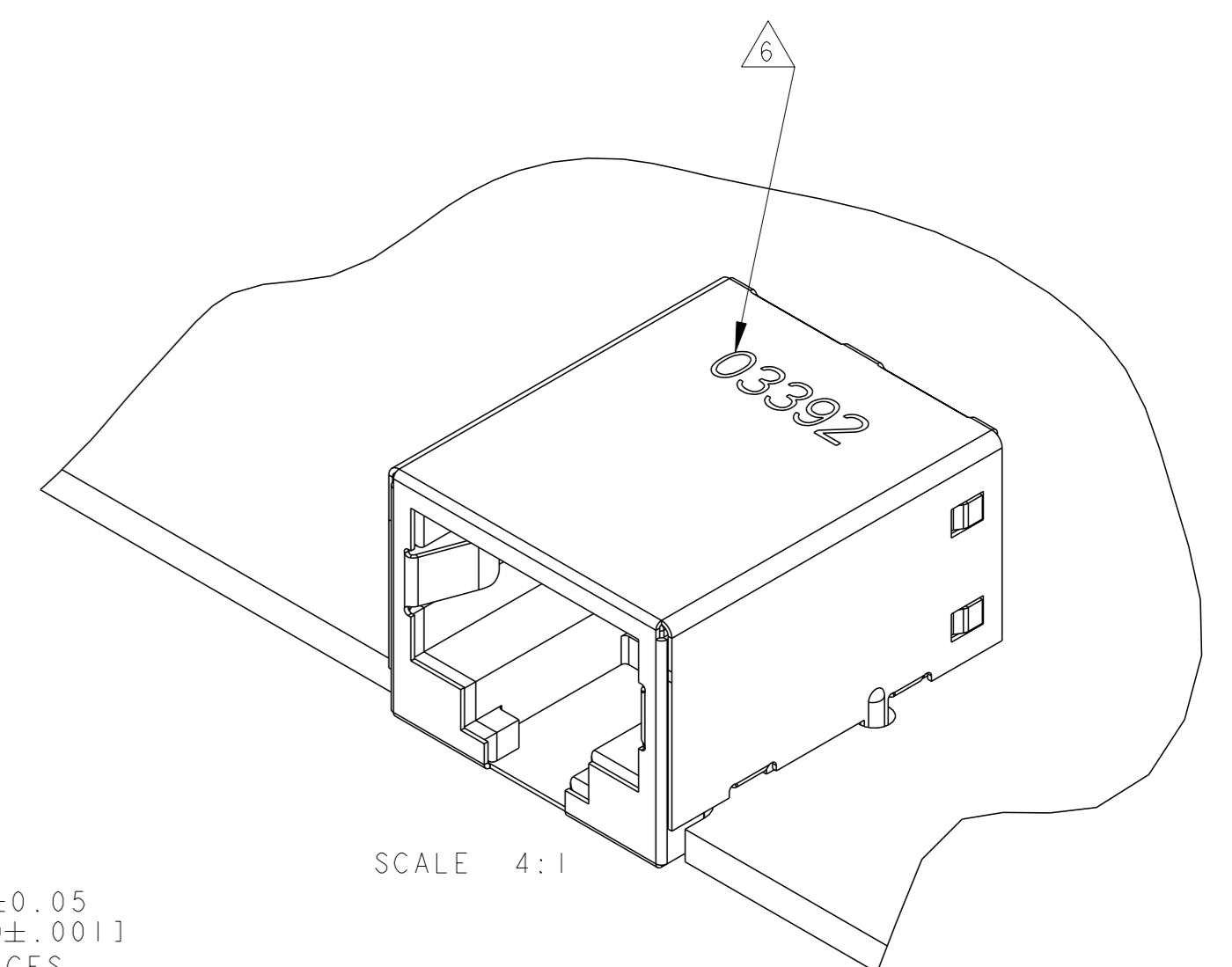
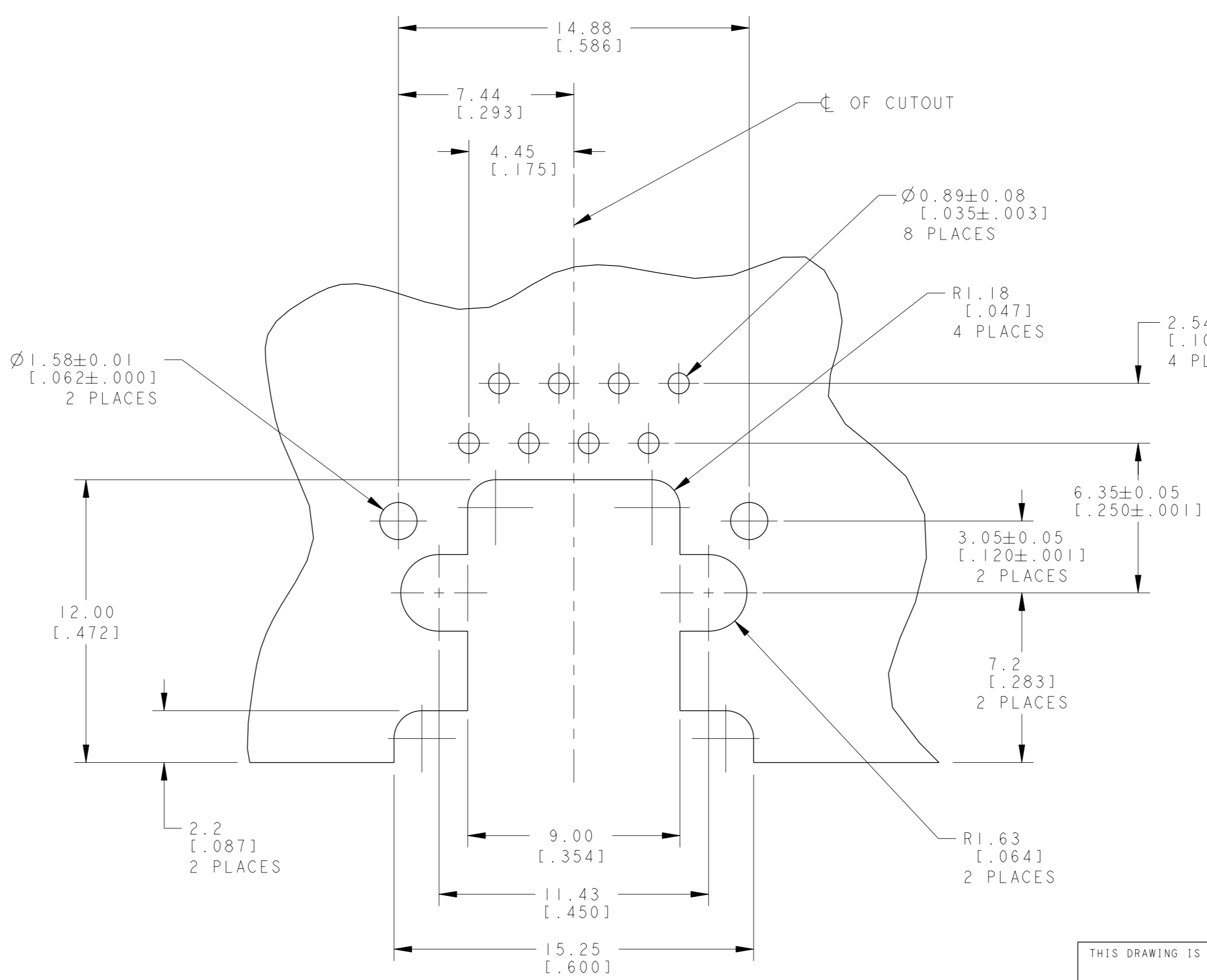
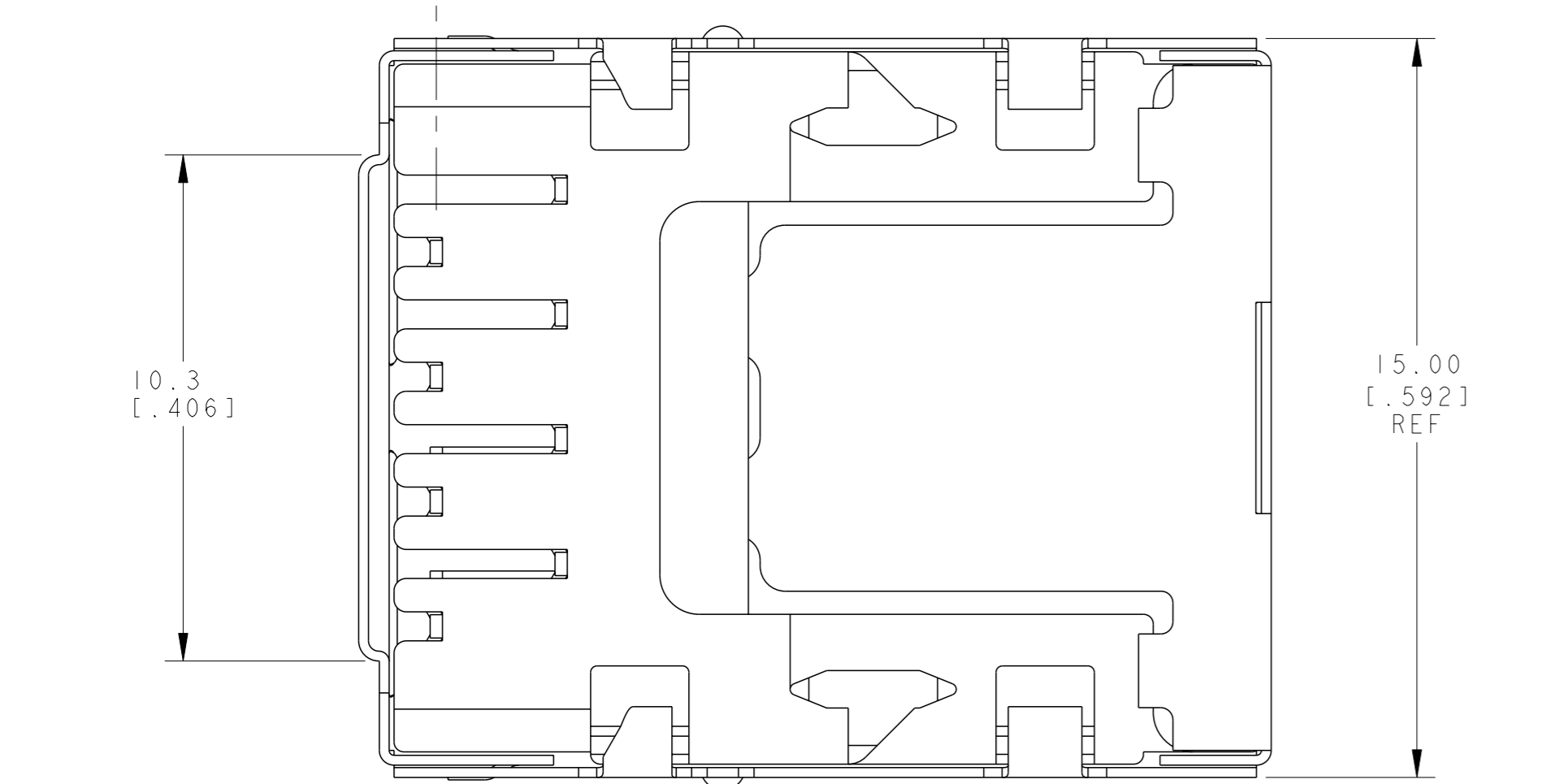


LOC	DIST	REVISIONS				
AA	22	REV	DESCRIPTION	DATE	OWN	APVD
		N1	REVISED PER ECO-11-005027	12MAY2011	RK	HMR
		P	REVISED PER ECO-14-015233	27APR2015	LL	SH
		R	ECO-16-011601	05AUG2016	LL	SH



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25[0.01] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm[0.000150] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER AREA, 1.27µm[0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[0.00050] MINIMUM THICK NICKEL. SHIELD - 0.1[0.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [0.00079-.000157] THICK TIN OVER 1.27 µm (.000050) MIN THICK NICKEL.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.
- 4 PACKAGED 66 ASSEMBLIES PER PVC TRAY, 396 PER BOX.
- 5 DIELECTRIC WITHSTANDING VOLTAGE BETWEEN SHIELD AND TERMINAL IS 1500 VAC.
- 6 MANUFACTURING DATE CODE:  
ORIENTED AND LOCATED APPROXIMATELY AS SHOWN. LASER PRINTING.  
TEXT HEIGHT APPROXIMATELY 2MM.  
FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR  
NEXT 2 DIGITS = MANUFACTURING WORK WEEK  
LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1
- 7 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25[0.01] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm[0.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm[0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[0.00050] MINIMUM THICK NICKEL. SHIELD - 0.1[0.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [0.00079-.000157] THICK TIN OVER 1.27 µm (.000050) MIN THICK NICKEL.
- 8 MATERIAL: HOUSING - POLYESTER LCP, NATURE, UL 94V-0, TERMINALS - 0.25[0.01] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm[0.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm[0.00050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[0.00050] MINIMUM THICK NICKEL. SHIELD - 0.1[0.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [0.00079-.000157] THICK TIN OVER 1.27 µm (.000050) MIN THICK NICKEL.
- 9 FOR 1116503-3 MATERIAL MARK: >LCP-GF30<.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SCALE 6:1

8	9	1116503-3
7		1116503-2
		1116503-1
MATERIAL/ FINISH		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: AHERON 07APR99	TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK: D. KEMPKA 07APR99	NAME: MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm WITHOUT PANEL TABS	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: D. KEMPKA 07APR99	PRODUCT SPEC: 108-1163	
0 PLC ±	1 PLC ±0.131(.005)	APPLICATION SPEC: 114-2048	SIZE: 114-2048	RESTRICTED TO: -
2 PLC ±	3 PLC ±	WEIGHT: 3.49 grams	CAGE CODE: 1116503	SCALE: 1:1
4 PLC ±	ANGLES ±	CUSTOMER DRAWING	SHEET: 1 of 1	REV: R

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)